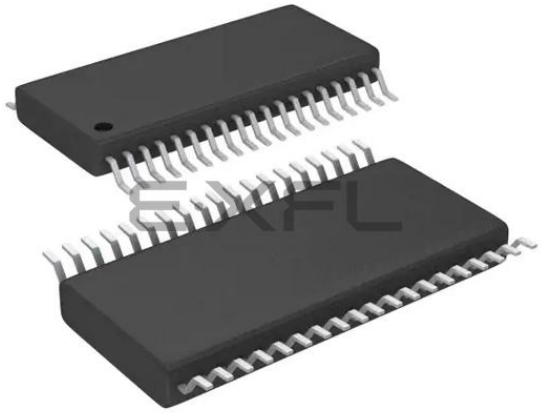

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Details	
Product Status	Last Time Buy
Core Processor	XC800
Core Size	8-Bit
Speed	25MHz
Connectivity	LINbus, SSI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	27
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	768 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 150°C (TA)
Mounting Type	Surface Mount
Package / Case	38-TFSOP (0.173", 4.40mm Width)
Supplier Device Package	PG-TSSOP-38-4
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/xc8664fra5vbelxuma1

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SAL-XC866 Variant Devices

The SAL-XC866 product family features devices with different configurations and program memory sizes, offering cost-effective solution for different application requirements.

The list of SAL-XC866 devices and their differences are summarized in **Table 1**.

Table 1 Device Summary

Device Type	Device Name	Power Supply (V)	P-Flash Size (Kbytes)	D-Flash Size (Kbytes)	LIN BSL Support
Flash[1)]	SAL-XC866L-4FRA	5.0	12	4	Yes
	SAL-XC866L-2FRA	5.0	4	4	Yes
	SAL-XC866L-4FRA	3.3	12	4	Yes
	SAL-XC866L-2FRA	3.3	4	4	Yes

1) The flash memory (P-Flash and D-Flash) can be used for code or data.

Ordering Information

The ordering code for Infineon Technologies microcontrollers provides an exact reference to the required product. This ordering code identifies:

- The derivative itself, i.e. its function set, the temperature range, and the supply voltage
- the package and the type of delivery

For the available ordering codes for the SAL-XC866, please refer to your responsible sales representative or your local distributor.

As this document refers to all the derivatives, some descriptions may not apply to a specific product. For simplicity all versions are referred to by the term SAL-XC866 throughout this document.

2.3 Pin Configuration

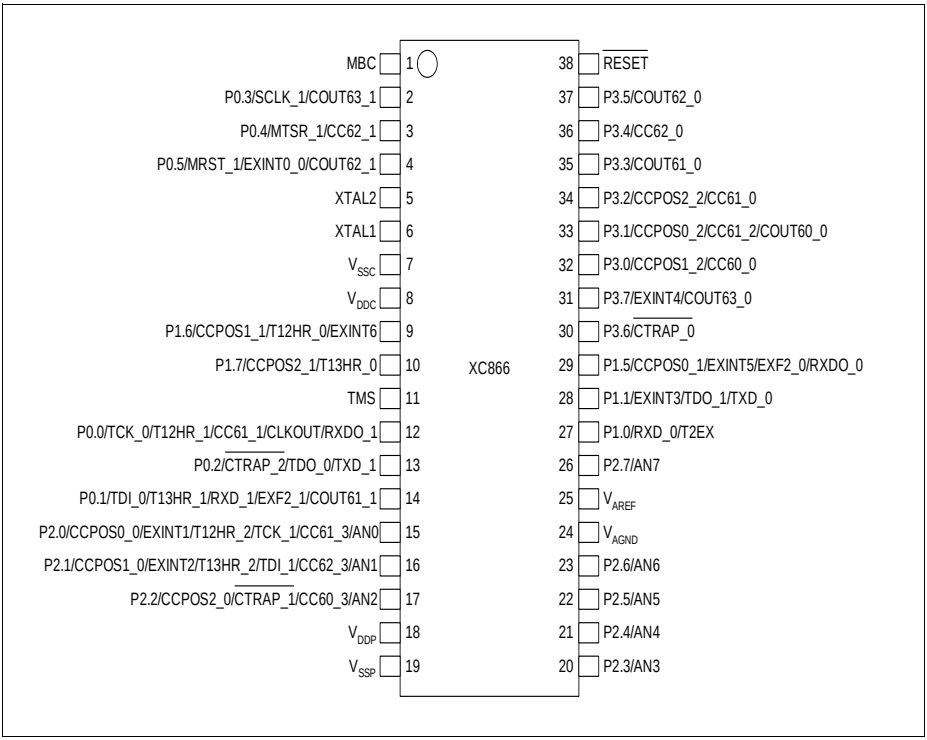


Figure 4 SAL-XC866 Pin Configuration, PG-TSSOP-38 Package (top view)

Table 8 Port Register Overview (cont'd)

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
$B1_H$	**P3_ALTSEL1** **Reset: 00_H** P3 Alternate Select 1 Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw
RMAP = 0, Page 3										
80_H	**P0_OD** **Reset: 00_H** P0 Open Drain Control Register	Bit Field	0		P5	P4	P3	P2	P1	P0
		Type	r		rw	rw	rw	rw	rw	rw
90_H	**P1_OD** **Reset: 00_H** P1 Open Drain Control Register	Bit Field	P7	P6	P5	0			P1	P0
		Type	rw	rw	rw	r			rw	rw
$B0_H$	**P3_OD** **Reset: 00_H** P3 Open Drain Control Register	Bit Field	P7	P6	P5	P4	P3	P2	P1	P0
		Type	rw	rw	rw	rw	rw	rw	rw	rw

The ADC SFRs can be accessed in the standard memory area (RMAP = 0).

Table 9 ADC Register Overview

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
RMAP = 0										
$D1_H$	**ADC_PAGE** **Reset: 00_H** Page Register for ADC	Bit Field	OP		STNR		0	PAGE		
		Type	w		w		r	rwh		
RMAP = 0, Page 0										
CA_H	**ADC_GLOBCTR** **Reset: 30_H** Global Control Register	Bit Field	ANON	DW	CTC		0			
		Type	rw	rw	rw		r			
CB_H	**ADC_GLOBSTR** **Reset: 00_H** Global Status Register	Bit Field	0		CHNR			0	SAMPLE	BUSY
		Type	r		rh			r	rh	rh
CC_H	**ADC_PRAR** **Reset: 00_H** Priority and Arbitration Register	Bit Field	ASEN1	ASEN0	0	ARBM	CSM1	PRIO1	CSM0	PRIO0
		Type	rw	rw	r	rw	rw	rw	rw	rw
CD_H	**ADC_LCBR** **Reset: $B7_H$** Limit Check Boundary Register	Bit Field	BOUND1				BOUND0			
		Type	rw				rw			
CE_H	**ADC_INPCR0** **Reset: 00_H** Input Class Register 0	Bit Field	STC							
		Type	rw							
CF_H	**ADC_ETRCR** **Reset: 00_H** External Trigger Control Register	Bit Field	SYNEN1	SYNEN0	ETRSEL1			ETRSEL0		
		Type	rw	rw	rw			rw		
RMAP = 0, Page 1										
CA_H	**ADC_CHCTR0** **Reset: 00_H** Channel Control Register 0	Bit Field	0	LCC			0		RESRSEL	
		Type	r	rw			r		rw	
CB_H	**ADC_CHCTR1** **Reset: 00_H** Channel Control Register 1	Bit Field	0	LCC			0		RESRSEL	
		Type	r	rw			r		rw	
CC_H	**ADC_CHCTR2** **Reset: 00_H** Channel Control Register 2	Bit Field	0	LCC			0		RESRSEL	
		Type	r	rw			r		rw	
CD_H	**ADC_CHCTR3** **Reset: 00_H** Channel Control Register 3	Bit Field	0	LCC			0		RESRSEL	
		Type	r	rw			r		rw	
CE_H	**ADC_CHCTR4** **Reset: 00_H** Channel Control Register 4	Bit Field	0	LCC			0		RESRSEL	
		Type	r	rw			r		rw	
CF_H	**ADC_CHCTR5** **Reset: 00_H** Channel Control Register 5	Bit Field	0	LCC			0		RESRSEL	
		Type	r	rw			r		rw	
$D2_H$	**ADC_CHCTR6** **Reset: 00_H** Channel Control Register 6	Bit Field	0	LCC			0		RESRSEL	
		Type	r	rw			r		rw	
$D3_H$	**ADC_CHCTR7** **Reset: 00_H** Channel Control Register 7	Bit Field	0	LCC			0		RESRSEL	
		Type	r	rw			r		rw	
RMAP = 0, Page 2										

Table 11 CCU6 Register Overview (cont'd)

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
FB_H	**CCU6_CC60SRH Reset: 00_H** Capture/Compare Shadow Register for Channel CC60 High	Bit Field	CC60SH							
		Type	rwh							
FC_H	**CCU6_CC61SRL Reset: 00_H** Capture/Compare Shadow Register for Channel CC61 Low	Bit Field	CC61SL							
		Type	rwh							
FD_H	**CCU6_CC61SRH Reset: 00_H** Capture/Compare Shadow Register for Channel CC61 High	Bit Field	CC61SH							
		Type	rwh							
FE_H	**CCU6_CC62SRL Reset: 00_H** Capture/Compare Shadow Register for Channel CC62 Low	Bit Field	CC62SL							
		Type	rwh							
FF_H	**CCU6_CC62SRH Reset: 00_H** Capture/Compare Shadow Register for Channel CC62 High	Bit Field	CC62SH							
		Type	rwh							
RMAP = 0, Page 1										
$9A_H$	**CCU6_CC63RL Reset: 00_H** Capture/Compare Register for Channel CC63 Low	Bit Field	CC63VL							
		Type	rh							
$9B_H$	**CCU6_CC63RH Reset: 00_H** Capture/Compare Register for Channel CC63 High	Bit Field	CC63VH							
		Type	rh							
$9C_H$	**CCU6_T12PRL Reset: 00_H** Timer T12 Period Register Low	Bit Field	T12PVL							
		Type	rwh							
$9D_H$	**CCU6_T12PRH Reset: 00_H** Timer T12 Period Register High	Bit Field	T12PVH							
		Type	rwh							
$9E_H$	**CCU6_T13PRL Reset: 00_H** Timer T13 Period Register Low	Bit Field	T13PVL							
		Type	rwh							
$9F_H$	**CCU6_T13PRH Reset: 00_H** Timer T13 Period Register High	Bit Field	T13PVH							
		Type	rwh							
$A4_H$	**CCU6_T12DTCL Reset: 00_H** Dead-Time Control Register for Timer T12 Low	Bit Field	DTM							
		Type	rw							
$A5_H$	**CCU6_T12DTCH Reset: 00_H** Dead-Time Control Register for Timer T12 High	Bit Field	0	DTR2	DTR1	DTR0	0	DTE2	DTE1	DTE0
		Type	r	rh	rh	rh	r	rw	rw	rw
$A6_H$	**CCU6_TCTR0L Reset: 00_H** Timer Control Register 0 Low	Bit Field	CTM	CDIR	STE12	T12R	T12 PRE	T12CLK		
		Type	rw	rh	rh	rh	rw	rw		
$A7_H$	**CCU6_TCTR0H Reset: 00_H** Timer Control Register 0 High	Bit Field	0		STE13	T13R	T13 PRE	T13CLK		
		Type	r		rh	rh	rw	rw		
FA_H	**CCU6_CC60RL Reset: 00_H** Capture/Compare Register for Channel CC60 Low	Bit Field	CC60VL							
		Type	rh							
FB_H	**CCU6_CC60RH Reset: 00_H** Capture/Compare Register for Channel CC60 High	Bit Field	CC60VH							
		Type	rh							
FC_H	**CCU6_CC61RL Reset: 00_H** Capture/Compare Register for Channel CC61 Low	Bit Field	CC61VL							
		Type	rh							

Table 12 SSC Register Overview

AB_H	**SSC_CONH** **Reset: 00_H** Control Register High *Programming Mode*	Bit Field	EN	MS	0	AREN	BEN	PEN	REN	TEN
		Type	rw	rw	r	rw	rw	rw	rw	rw
	Operating Mode	Bit Field	EN	MS	0	BSY	BE	PE	RE	TE
		Type	rw	rw	r	rh	rwh	rwh	rwh	rwh
AC_H	**SSC_TBL** **Reset: 00_H** Transmitter Buffer Register Low	Bit Field	TB_VALUE							
		Type	rw							
AD_H	**SSC_RBL** **Reset: 00_H** Receiver Buffer Register Low	Bit Field	RB_VALUE							
		Type	rh							
AE_H	**SSC_BRL** **Reset: 00_H** Baudrate Timer Reload Register Low	Bit Field	BR_VALUE[7:0]							
		Type	rw							
AF_H	**SSC_BRH** **Reset: 00_H** Baudrate Timer Reload Register High	Bit Field	BR_VALUE[15:8]							
		Type	rw							

The OCDS SFRs can be accessed in the mapped memory area (RMAP = 1).

Table 13 OCDS Register Overview

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
RMAP = 1										
$E9_H$	**MMCR2** **Reset: $0U_H$** Monitor Mode Control Register 2	Bit Field	EXBC_P	EXBC	MBCON_P	MBCON	MMEP_P	MMEP	MMODE	JENA
		Type	w	rw	w	rwh	w	rwh	rh	rh
$F1_H$	**MMCR** **Reset: 00_H** Monitor Mode Control Register	Bit Field	MEXIT_P	MEXIT	MSTEP_P	MSTEP	MRAMS_P	MRAMS	TRF	RRF
		Type	w	rwh	w	rw	w	rwh	rh	rh
$F2_H$	**MMSR** **Reset: 00_H** Monitor Mode Status Register	Bit Field	MBCAM	MBCIN	EXBF	SWBF	HWB3F	HWB2F	HWB1F	HWB0F
		Type	rw	rh	rwh	rwh	rwh	rwh	rwh	rwh
$F3_H$	**MMBPCR** **Reset: 00_H** BreakPoints Control Register	Bit Field	SWBC	HWB3C		HWB2C		HWB1C	HWB0C	
		Type	rw	rw		rw		rw	rw	
$F4_H$	**MMICR** **Reset: 00_H** Monitor Mode Interrupt Control Register	Bit Field	DVECT	DRETR	0		MMUIE_P	MMUIE	RRIE_P	RRIE
		Type	rwh	rwh	r		w	rw	w	rw
$F5_H$	**MMDR** **Reset: 00_H** Monitor Mode Data Register *Receive*	Bit Field	MMRR							
		Type	rh							
	Transmit	Bit Field	MMTR							
		Type	w							
$F6_H$	**HWBPSR** **Reset: 00_H** Hardware Breakpoints Select Register	Bit Field	0			BPSEL_P	BPSEL			
		Type	r			w	rw			
$F7_H$	**HWBPDR** **Reset: 00_H** Hardware Breakpoints Data Register	Bit Field	HWBPxx							
		Type	rw							

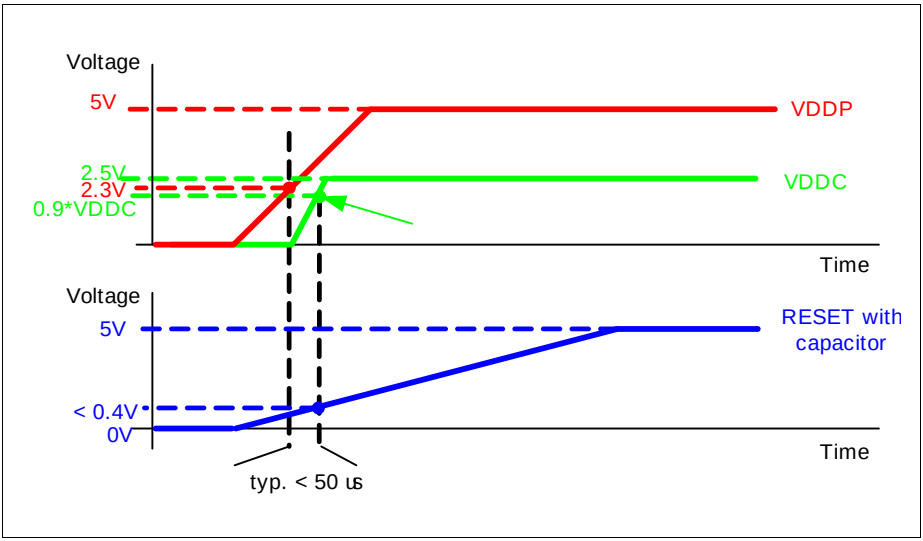


Figure 21 V_{DDP}, V_{DDC} and V_{RESET} during Power-on Reset

The second type of reset in SAL-XC866 is the hardware reset. This reset function can be used during normal operation or when the chip is in power-down mode. A reset input pin $\overline{\text{RESET}}$ is provided for the hardware reset. To ensure the recognition of the hardware reset, pin $\overline{\text{RESET}}$ must be held low for at least 100 ns.

The Watchdog Timer (WDT) module is also capable of resetting the device if it detects a malfunction in the system.

Another type of reset that needs to be detected is a reset while the device is in power-down mode (wake-up reset). While the contents of the static RAM are undefined after a power-on reset, they are well defined after a wake-up reset from power-down mode.

3.7.1 Module Reset Behavior

Table 17 shows how the functions of the SAL-XC866 are affected by the various reset types. A "■" means that this function is reset to its default state.

Table 17 Effect of Reset on Device Functions

Module/ Function	Wake-Up Reset	Watchdog Reset	Hardware Reset	Power-On Reset	Brownout Reset
CPU Core	■	■	■	■	■
Peripherals	■	■	■	■	■
On-Chip Static RAM	Not affected, reliable	Not affected, reliable	Not affected, reliable	Affected, un-reliable	Affected, un-reliable
Oscillator, PLL	■	Not affected	■	■	■
Port Pins	■	■	■	■	■
EVR	The voltage regulator is switched on	Not affected	■	■	■
FLASH	■	■	■	■	■
NMI	Disabled	Disabled	■	■	■

3.7.2 Booting Scheme

When the SAL-XC866 is reset, it must identify the type of configuration with which to start the different modes once the reset sequence is complete. Thus, boot configuration information that is required for activation of special modes and conditions needs to be applied by the external world through input pins. After power-on reset or hardware reset, the pins MBC, TMS and P0.0 collectively select the different boot options. Table 18 shows the available boot options in the SAL-XC866.

Table 18 SAL-XC866 Boot Selection

MBC	TMS	P0.0	Type of Mode	PC Start Value
1	0	x	User Mode; on-chip OSC/PLL non-bypassed	0000_H
0	0	x	BSL Mode; on-chip OSC/PLL non-bypassed	0000_H
0	1	0	OCDS Mode[1]; on-chip OSC/PLL non-bypassed	0000_H
1	1	0	Standalone User (JTAG) Mode[2]; on-chip OSC/PLL non-bypassed (normal)	0000_H

1) The OCDS mode is not accessible if Flash is protected.
2) Normal user mode with standard JTAG (TCK,TDI,TDO) pins for hot-attach purpose.

3.9 Power Saving Modes

The power saving modes of the SAL-XC866 provide flexible power consumption through a combination of techniques, including:

- Stopping the CPU clock
- Stopping the clocks of individual system components
- Reducing clock speed of some peripheral components
- Power-down of the entire system with fast restart capability

After a reset, the active mode (normal operating mode) is selected by default (see **Figure 25**) and the system runs in the main system clock frequency. From active mode, different power saving modes can be selected by software. They are:

- Idle mode
- Slow-down mode
- Power-down mode

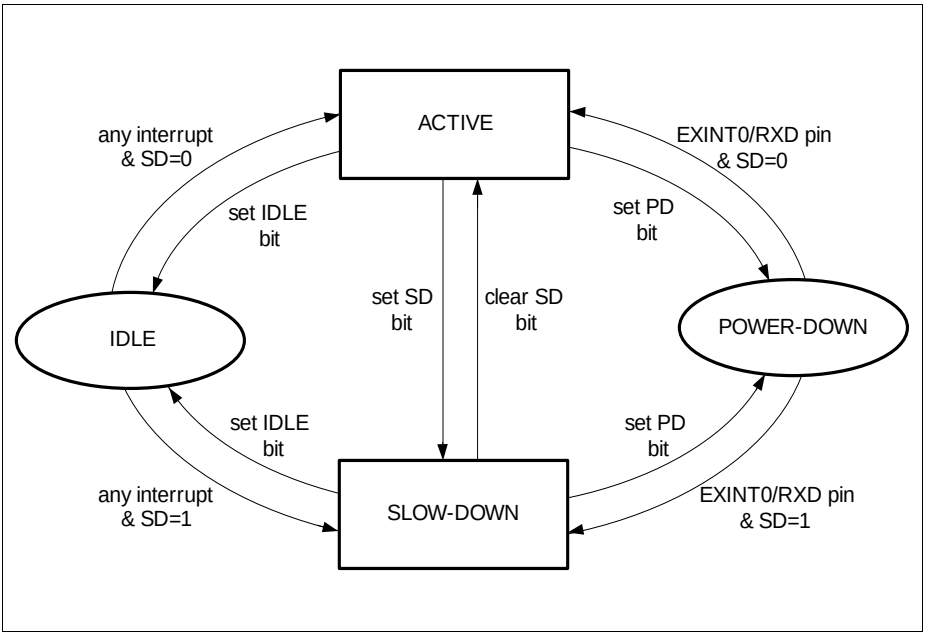


Figure 25 Transition between Power Saving Modes

Table 23 lists the possible watchdog time range that can be achieved for different module clock frequencies. Some numbers are rounded to 3 significant digits.

Table 23 Watchdog Time Ranges

Reload value in WDTREL	Prescaler for f_{PCLK}	
	2 (WDTIN = 0)	**128 (WDTIN = 1)**
	25 MHz	**25 MHz**
FF_H	20.5 µs	1.31 ms
$7F_H$	2.64 ms	169 ms
00_H	5.24 ms	336 ms

- 8-bit reload value (BR_VALUE) for the baud rate timer defined by register BG

The following formulas calculate the final baud rate without and with the fractional divider respectively:

$$\text{baud rate} = \frac{f_{PCLK}}{16 \times 2^{BRPRE} \times (BR\_VALUE + 1)} \quad \text{where} \quad 2^{BRPRE} \times (BR\_VALUE + 1) > 1$$

$$\text{baud rate} = \frac{f_{PCLK}}{16 \times 2^{BRPRE} \times (BR\_VALUE + 1)} \times \frac{STEP}{256}$$

The maximum baud rate that can be generated is limited to $f_{PCLK}/32$. Hence, for a module clock of 25 MHz, the maximum achievable baud rate is 0.78 MBaud.

Standard LIN protocol can support a maximum baud rate of 20kHz, the baud rate accuracy is not critical and the fractional divider can be disabled. Only the prescaler is used for auto baud rate calculation. For LIN fast mode, which supports the baud rate of 20kHz to 115.2kHz, the higher baud rates require the use of the fractional divider for greater accuracy.

Table 25 lists the various commonly used baud rates with their corresponding parameter settings and deviation errors. The fractional divider is disabled and a module clock of 25 MHz is used.

Table 25 Typical Baud rates for UART with Fractional Divider disabled

Baud rate	Prescaling Factor (2^{BRPRE})	Reload Value (BR_VALUE + 1)	Deviation Error
19.2 kBaud	1 (BRPRE=000_B)	81 (51_H)	-0.47 %
9600 Baud	1 (BRPRE=000_B)	162 ($A2_H$)	-0.47 %
4800 Baud	2 (BRPRE=001_B)	162 ($A2_H$)	-0.47 %
2400 Baud	4 (BRPRE=010_B)	162 ($A2_H$)	-0.47 %

The fractional divider allows baud rates of higher accuracy (lower deviation error) to be generated. **Table 26** lists the resulting deviation errors from generating a baud rate of 115.2 kHz, using different module clock frequencies. The fractional divider is enabled (fractional divider mode) and the corresponding parameter settings are shown.

3.11.2 Baud Rate Generation using Timer 1

In UART modes 1 and 3, Timer 1 can be used for generating the variable baud rates. In theory, this timer could be used in any of its modes. But in practice, it should be set into auto-reload mode (Timer 1 mode 2), with its high byte set to the appropriate value for the required baud rate. The baud rate is determined by the Timer 1 overflow rate and the value of SMOD as follows:

[3.1]

$$\text{Mode 1, 3 baud rate} = \frac{2^{SMOD} \times f_{PCLK}}{32 \times 2 \times (256 - TH1)}$$

3.12 Normal Divider Mode (8-bit Auto-reload Timer)

Setting bit FDM in register FDCON to 1 configures the fractional divider to normal divider mode, while at the same time disables baud rate generation (see **Figure 28**). Once the fractional divider is enabled (FDEN = 1), it functions as an 8-bit auto-reload timer (with no relation to baud rate generation) and counts up from the reload value with each input clock pulse. Bit field RESULT in register FDRES represents the timer value, while bit field STEP in register FDSTEP defines the reload value. At each timer overflow, an overflow flag (FDCON.NDOV) will be set and an interrupt request generated. This gives an output clock f_{MOD} that is 1/n of the input clock f_{DIV}, where n is defined by 256 - STEP.

The output frequency in normal divider mode is derived as follows:

[3.2]

$$f_{MOD} = f_{DIV} \times \frac{1}{256 - STEP}$$

3.13 LIN Protocol

The UART can be used to support the Local Interconnect Network (LIN) protocol for both master and slave operations. The LIN baud rate detection feature provides the capability to detect the baud rate within LIN protocol using Timer 2. This allows the UART to be synchronized to the LIN baud rate for data transmission and reception.

LIN is a holistic communication concept for local interconnected networks in vehicles. The communication is based on the SCI (UART) data format, a single-master/multiple-slave concept, a clock synchronization for nodes without stabilized time base. An attractive feature of LIN is self-synchronization of the slave nodes without a crystal or ceramic resonator, which significantly reduces the cost of hardware platform. Hence, the baud rate must be calculated and returned with every message frame.

The structure of a LIN frame is shown in **Figure 29**. The frame consists of the:

- header, which comprises a Break (13-bit time low), Synch Byte (55_H), and ID field
- response time
- data bytes (according to UART protocol)
- checksum

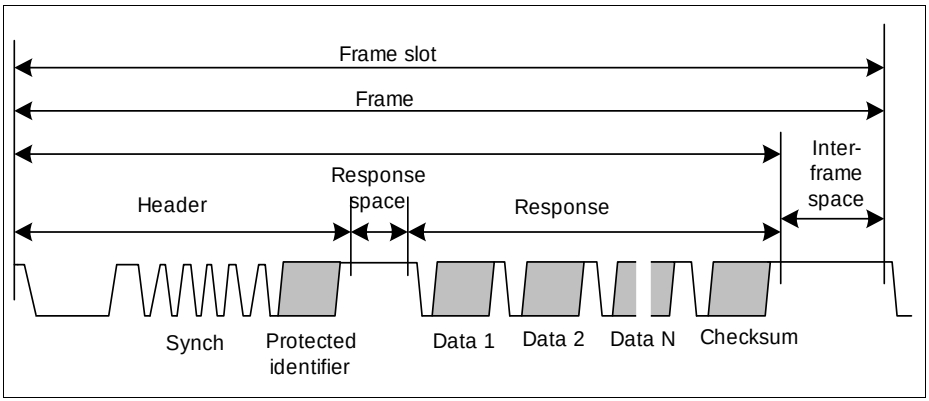


Figure 29 Structure of LIN Frame

3.13.1 LIN Header Transmission

LIN header transmission is only applicable in master mode. In the LIN communication, a master task decides when and which frame is to be transferred on the bus. It also identifies a slave task to provide the data transported by each frame. The information needed for the handshaking between the master and slave tasks is provided by the master task through the header portion of the frame.

The header consists of a break and synch pattern followed by an identifier. Among these three fields, only the break pattern cannot be transmitted as a normal 8-bit UART data.

The break must contain a dominant value of 13 bits or more to ensure proper synchronization of slave nodes.

In the LIN communication, a slave task is required to be synchronized at the beginning of the protected identifier field of frame. For this purpose, every frame starts with a sequence consisting of a break field followed by a synch byte field. This sequence is unique and provides enough information for any slave task to detect the beginning of a new frame and be synchronized at the start of the identifier field.

Upon entering LIN communication, a connection is established and the transfer speed (baud rate) of the serial communication partner (host) is automatically synchronized in the following steps:

STEP 1: Initialize interface for reception and timer for baud rate measurement

STEP 2: Wait for an incoming LIN frame from host

STEP 3: Synchronize the baud rate to the host

STEP 4: Enter for Master Request Frame or for Slave Response Frame

*Note: Re-synchronization and setup of baud rate are always done for **every** Master Request Header or Slave Response Header LIN frame.*

3.18 Analog-to-Digital Converter

The SAL-XC866 includes a high-performance 10-bit Analog-to-Digital Converter (ADC) with eight multiplexed analog input channels. The ADC uses a successive approximation technique to convert the analog voltage levels from up to eight different sources. The analog input channels of the ADC are available at Port 2.

Features:

- Successive approximation
- 8-bit or 10-bit resolution
- Eight analog channels
- Four independent result registers
- Result data protection for slow CPU access (wait-for-read mode)
- Single conversion mode
- Autoscan functionality
- Limit checking for conversion results
- Data reduction filter (accumulation of up to 2 conversion results)
- Two independent conversion request sources with programmable priority
- Selectable conversion request trigger
- Flexible interrupt generation with configurable service nodes
- Programmable sample time
- Programmable clock divider
- Cancel/restart feature for running conversions
- Integrated sample and hold circuitry
- Compensation of offset errors
- Low power modes

4.2 DC Parameters

4.2.1 Input/Output Characteristics

Table 33 Input/Output Characteristics (Operating Conditions apply)

Parameter	Symbol		Limit Values		Unit	Test Conditions
			min.	max.		
V_{DDP} = 5V Range						
Output low voltage	V_{OL}	CC	–	1.0	V	I_{OL} = 15 mA
			–	0.4	V	I_{OL} = 5 mA
Output high voltage	V_{OH}	CC	V_{DDP} - 1.0	–	V	I_{OH} = -15 mA
			V_{DDP} - 0.4	–	V	I_{OH} = -5 mA
Input low voltage on port pins (all except P0.0 & P0.1)	V_{ILP}	SR	–	0.3 × V_{DDP}	V	CMOS Mode
Input low voltage on P0.0 & P0.1	V_{ILP0}	SR	-0.2	0.3 × V_{DDP}	V	CMOS Mode
Input low voltage on $\overline{\text{RESET}}$ pin	V_{ILR}	SR	–	0.3 × V_{DDP}	V	CMOS Mode
Input low voltage on TMS pin	V_{ILT}	SR	–	0.3 × V_{DDP}	V	CMOS Mode
Input high voltage on port pins (all except P0.0 & P0.1)	V_{IHP}	SR	0.7 × V_{DDP}	–	V	CMOS Mode
Input high voltage on P0.0 & P0.1	V_{IHP0}	SR	0.7 × V_{DDP}	V_{DDP}	V	CMOS Mode
Input high voltage on $\overline{\text{RESET}}$ pin	V_{IHR}	SR	0.7 × V_{DDP}	–	V	CMOS Mode
Input high voltage on TMS pin	V_{IHT}	SR	0.75 × V_{DDP}	–	V	CMOS Mode
Input Hysteresis[1] on Port Pins	HYS	CC	0.08 × V_{DDP}	–	V	CMOS Mode
Input Hysteresis[1] on XTAL1	$HYSX$	CC	0.07 × V_{DDC}	–	V	

4.2.2 Supply Threshold Characteristics

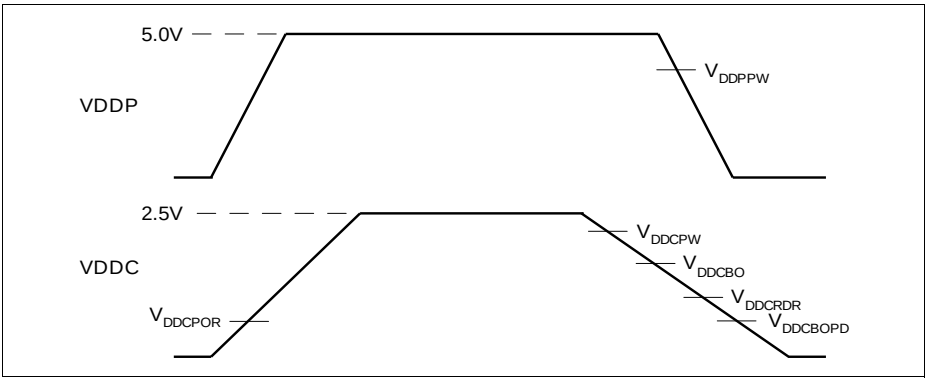


Figure 35 Supply Threshold Parameters

Table 34 Supply Threshold Parameters (Operating Conditions apply)

Parameters	Symbol		Limit Values			Unit
			min.	typ.	max.	
V_{DDC} prewarning voltage[1]	V_{DDCPW}	CC	2.2	2.3	2.4	V
V_{DDC} brownout voltage in active mode[1]	V_{DDCBO}	CC	2.0	2.1	2.2	V
RAM data retention voltage	V_{DDCRDR}	CC	0.9	1.0	1.1	V
V_{DDC} brownout voltage in power-down mode[2]	$V_{DDCBOPD}$	CC	1.3	1.5	1.7	V
V_{DDP} prewarning voltage[3]	V_{DDPPW}	CC	3.3	4.0	4.65	V
Power-on reset voltage[2][4]	V_{DDCPOR}	CC	1.3	1.5	1.7	V

1) Detection is disabled in power-down mode.

2) Detection is enabled in both active and power-down mode.

3) Detection is enabled for external power supply of 5.0V
Detection must be disabled for external power supply of 3.3V.

4) The reset of EVR is extended by 300 µs typically after the VDDC reaches the power-on reset voltage.

Table 37 Power Down Current (Operating Conditions apply)

Parameter	Symbol	Limit Values		Unit	Test Condition
		typ.[1]	max.[2]		
Power-Down Mode[3]	I_{PDP}	1	10	µA	T_A = + 25 °C.[4]
		-	30	µA	T_A = + 85 °C.[4][5]

1) The typical I_{PDP} values are measured at V_{DDP} = 5.0 V.

2) The maximum I_{PDP} values are measured at V_{DDP} = 5.5 V.

3) I_{PDP} (power-down mode) has a maximum value of 500 µA at T_A = + 150 °C.

4) I_{PDP} (power-down mode) is measured with: $\overline{\text{RESET}}$ = V_{DDP}, V_{AGND}= V_{SS}, RXD/INT0 = V_{DDP}; rest of the ports are programmed to be input with either internal pull devices enabled or driven externally to ensure no floating inputs.

5) Not subject to production test, verified by design/characterization.

4.3.6 SSC Master Mode Timing

Table 43 SSC Master Mode Timing (Operating Conditions apply; C_L = 50 pF)

Parameter	Symbol		Limit Values		Unit
			min.	max.	
SCLK clock period[1]	t_0	CC	2*T_{SSC} [2]	–	ns
MTSR delay from SCLK[1] ↓	t_1	CC	0	8	ns
MRST setup to SCLK[1] ↓	t_2	SR	22	–	ns
MRST hold from SCLK[1] ↓	t_3	SR	0	–	ns

1) Not all parameters are 100% tested, but are verified by design/characterization and test correlation.

2) $T_{SSCmin} = T_{CPU} = 1/f_{CPU}$. When f_{CPU} = 25 MHz, t_0 = 80 ns. T_{CPU} is the CPU clock period.

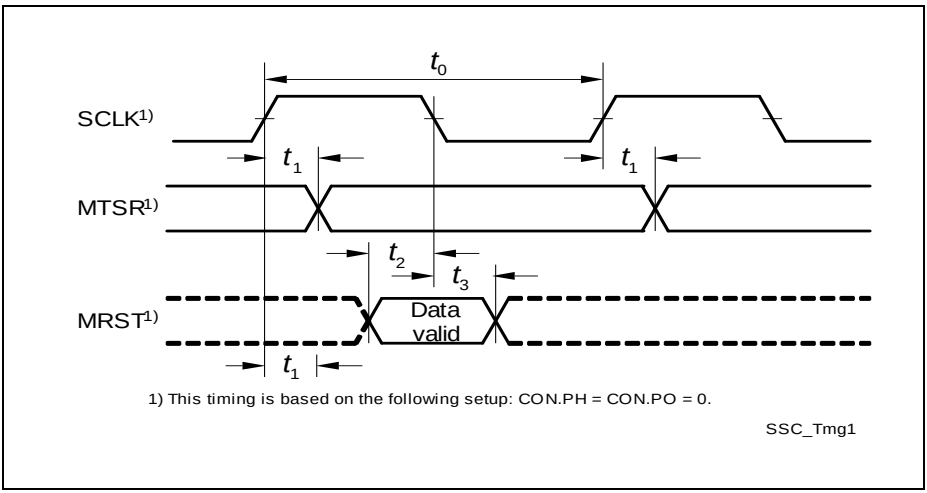
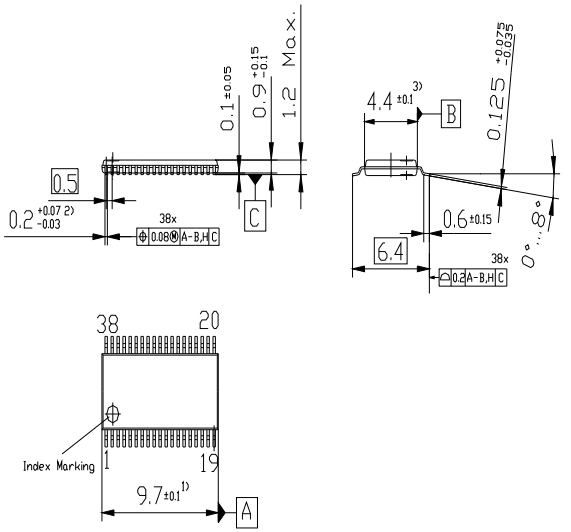


Figure 44 SSC Master Mode Timing

5.2 Package Outline



1) DOES NOT INCLUDE PLASTIC OR METAL PROTRUSION OF 0.15 MAX. PER SIDE

2) DOES NOT INCLUDE DAMBAR PROTRUSION OF 0.08 MAX. PER SIDE

3) DOES NOT INCLUDE PLASTIC OR METAL PROTRUSION OF 0.25 MAX. PER SIDE

Figure 45 PG-TSSOP-38-4 Package Outline